

**AMENDMENTS TO THE CLAIMS**

1. (Previously Presented): A fabricating method for an array substrate of a liquid crystal display device, the method comprising:

    forming a gate line including a gate electrode on a substrate;

    forming a gate-insulating layer on the substrate, the gate-insulating layer covering the gate line and gate electrode;

    forming an active layer on the gate-insulating layer;

    forming a data line, a source electrode and a drain electrode on the active layer;

    forming a passivation layer on the gate-insulating layer, the passivation layer covering the data line, source electrode and drain electrode;

    dry-etching a surface of the passivation layer with a gas without using a photo mask such that the surface is embossed and has a plurality of random uneven portions; and

    forming a reflective electrode on the embossed surface of the passivation layer such that an exterior surface of the reflective electrode is embossed.

2. (Original): The method of claim 1, wherein the gas used for the dry-etching is a mixture gas of SF<sub>6</sub> + O<sub>2</sub>.

3. (Original): The method of claim 1, wherein the gas used for the dry-etching is a mixture gas of CF<sub>4</sub> + O<sub>2</sub>.

4. (Original): The method of claim 1, wherein the gas used for the dry-etching is O<sub>2</sub> gas.

5. (Original): The method of claim 1, wherein the passivation layer includes an organic insulating material.

6. (Original): The method of claim 5, wherein the organic insulating material is benzocyclobutene (BCB).

7. (Original): The method of claim 1, wherein the reflective electrode is an opaque conductive metal.

8. (Original): The method of claim 7, wherein the opaque conductive metal is an aluminum based metal.

9. (Original): The method of claim 1, further including forming a contact hole in the passivation layer prior to forming a reflective electrode on the embossed surface of the passivation layer such that an exterior surface of the reflective electrode is embossed.

10. (Original): The method of claim 1, further including forming a contact hole in the passivation layer prior to dry-etching the surface of the passivation layer.

11. (Previously Presented): A liquid crystal display device comprising:  
upper and lower substrates with a liquid crystal layer interposed therebetween;  
a gate line and a gate electrode on the lower substrate;  
a gate-insulating layer on the lower substrate, the gate-insulating layer covering the gate line and gate electrode;  
an active layer on the gate-insulating layer;  
a source electrode and a drain electrode on the active layer;  
a data line on the gate-insulating layer;  
a passivation layer on the data line, source electrode, and drain electrode, an entire surface of the passivation layer being embossed by a dry etching and having a plurality of random uneven portions; and  
an embossed reflective electrode on the passivation layer.

12. (Original): The device of claim 11, wherein the passivation layer includes an organic insulating material.

13. (Original): The device of claim 11, wherein the organic insulating material is benzocyclobutene (BCB).

14. (Original): The device of claim 11, wherein the reflective electrode is an opaque conductive metal.

15. (Original): The device of claim 14, wherein the opaque conductive metal is an aluminum based metal.

16. (Original): A method of fabricating an array substrate for a liquid crystal display device, the method comprising:

forming a gate line including a gate electrode on a substrate;

forming a first insulating layer on the substrate, the first insulating layer covering the gate line and gate electrode;

forming an active layer on the first insulating layer;

forming a data line, a source electrode and a drain electrode on the active layer;

forming a second insulating layer on the data line, source electrode and drain electrode;

forming a first contact hole in the second insulating layer, exposing a first portion of the drain electrode;

forming a transparent electrode contacting the drain electrode via the first contact hole;

forming a passivation layer on the first insulating layer and transparent electrode;

forming a second contact hole in the passivation layer and the second insulating layer, exposing a second portion of the drain electrode;

dry-etching a surface of the passivation layer with a gas such that the surface is embossed; and

forming a reflective electrode on the embossed surface of the passivation layer such that an exterior surface of the reflective electrode is embossed.

17. (Original): The method of claim 16, wherein the gas used for the dry-etching is a mixture gas of SF<sub>6</sub> + O<sub>2</sub>.

18. (Original): The method of claim 16, wherein the gas used for the dry-etching is a mixture gas of CF<sub>4</sub> + O<sub>2</sub>.

19. (Original): The method of claim 16, wherein the gas used for the dry-etching is O<sub>2</sub> gas.

20. (Original): The method of claim 16, wherein the passivation layer includes an organic

insulating material.

21. (Original): The method of claim 20, wherein the organic insulating material is benzocyclobutene (BCB).

22. (Original): The method of claim 16, wherein the reflective electrode is an opaque conductive metal.

23. (Original): The method of claim 22, wherein the opaque conductive metal is an aluminum based metal.

24. (Original): A liquid crystal display device comprising:

- upper and lower substrates with a liquid crystal layer interposed therebetween;
- a gate line and a gate electrode on the lower substrate;
- a first insulating layer on the lower substrate, the first insulating layer covering the gate line and gate electrode;
- an active layer on the gate-insulating layer;
- a source electrode and a drain electrode on the active layer; a data line on the gate-insulating layer;
- a second insulating layer on the data line, source electrode and drain electrode;
- a transparent electrode on the second insulating layer;
- a passivation layer on the second insulating layer and the transparent electrode; and
- an embossed reflective electrode on the passivation layer.

25. (Original): The device of claim 24, wherein the passivation layer includes an organic insulating material.

26. (Original): The device of claim 24, wherein the organic insulating material is benzocyclobutene (BCB).

27. (Original): The device of claim 24, wherein the reflective electrode is an opaque conductive metal.

28. (Original): The device of claim 27, wherein the opaque conductive metal is an aluminum based metal.

29. (New): The method of claim 2, wherein the surface of the passivation layer is dry-etched for a time period shorter than about 50 sec.

30. (New): The method of claim 3, wherein the surface of the passivation layer is dry-etched for a time period shorter than about 50 sec.

31. (New): The method of claim 4, wherein the surface of the passivation layer is dry-etched for a time period shorter than about 50 sec.